ABSTRACT

A very small-size/large-capacity DRAM module constructed by mounting a resin package (2A), in which a predetermined number of lead frames mounted with semiconductor chips are stacked and encapsulated altogether, on a mother socket (3A) and by electrically connecting the leads (6) of the lead frames led out from the side of the resin package (2A), and the module leads (9) of the mother socket (3A) extending in the direction perpendicular to the extending direction of the leads (6).